

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Wafer Size Change for MAX6509, MAX6510, MAX6033 Products
Publication Date:	8-Jan-2024
Effectivity Date:	7-April-2024 (the earliest date that a customer could expect to receive changed material)
Revision Description:	Initial Release.

Description Of Change:

Analog Devices Beaverton/USA is moving from current 6-inch wafer size (process S12) to 8-inch wafer size (process B12).
Note: B12 process qualification has been completed in 2006 and has been running in Beaverton fab since.
This is a wafer size change only.

Reason For Change:

Analog Devices Beaverton/USA fab is moving to the 8-inch process to ensure adequate capacity for supply continuity.

Impact of the change (positive or negative) on fit, form, function & reliability:

The Form/Fit/Function of the devices is unchanged.

Product Identification (this section will describe how to identify the changed material):

Analog Devices maintains full traceability by device marking, packaging labels and shipment documents.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Qualification Report Summary

[R060002FQ_B12_Qual.pdf](#)

Attachment 2: Type: Test Correlation Report

[ADBN_S12_B12 Equivalency_PCN.pdf](#)

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file